
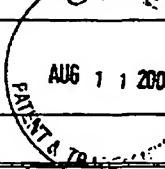
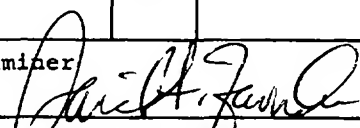


Form PTO-1449					Atty Docket No.		Serial No.	
U.S. Department of Commerce, Patent and Trademark Office					BDG005-1		10/059,686	
<b>INFORMATION DISCLOSURE STATEMENT</b> (Use several sheets if necessary)					Applicant			
					Cheng-Lien Chiang			
					Filing Date		Group Art Unit	
					January 29, 2002		2812	
<b>U.S. Patent Documents</b>								
*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate	
AT	AA	6,198,171	03/2001	Huang et al.	257	787		
AT	AB	6,218,728	04/2001	Kimura	257	693		
	AC							
	AD							
	AE							
	AF							
	AG							
	AH							
	AI							
	AJ							
	AK							
	AL							
	AM							
<b>Foreign Patent Documents</b>								
							Translation	
		Document	Date	Country	Class	Subclass	Yes	No
AT	AN	JP-06097352	04/1994	Japan	H01L	23/50	X	
	AO							
<b>Other Art (Including Author, Title, Date, Pertinent Pages, Etc.)</b>								
	AP							
	AQ							
Examiner		Date Considered						
AT		12/6/3						
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<b>U.S. Patent Documents</b>								
*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate	
ME	AA	6,001,671	12/1999	Fjelstad	438	112		
ME	AB	6,025,650	02/2000	Tsuji et al.	257	786		
ME	AC	6,281,568	08/2001	Glenn et al.	257	684		
	AD							
	AE							
	AF							
	AG							
	AH							
	AI							
	AJ							
	AK							
	AL							
	AM							
<b>Foreign Patent Documents</b>								
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<b>Other Art (Including Author, Title, Date, Pertinent Pages, Etc.)</b>								
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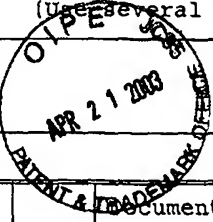
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					Filing Date January 29, 2002		Group Art Unit <u>2812 2827</u>	

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*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
072	AA	3,627,901	12/1971	Happ	174	52 PE	
	AB	3,678,385	07/1972	Bruner	324	158 F	
	AC	3,930,114	12/1975	Hodge	174	52 FP	
	AD	4,506,238	03/1985	Endoh et al.	333	138	
	AE	5,157,480	10/1992	McShane et al.	357	74	
	AF	5,207,102	05/1993	Takahashi et al.	73	727	
	AG	5,436,500	07/1995	Park et al.	257	696	
	AH	5,677,566	10/1997	King et al.	257	666	
	AI	5,866,939	02/1999	Shin et al.	257	666	
	AJ	5,894,107	04/1999	Lee et al.	174	52.2	
	AK	5,951,804	09/1999	Kweon et al.	156	244.12	
	AL	6,114,770	09/2000	Akram et al.	257	784	
	AM	6,130,116	10/2000	Smith et al.	438	127	
	AN	6,232,152	05/2001	DiStefano et al.	438	124	
	AO	6,297,543	10/2001	Hong et al.	257	666	
	AP	6,303,997	10/2001	Lee	257	778	
	AQ	6,326,700	12/2001	Bai et al.	257	790	
	AR	6,445,077	09/2002	Choi et al.	257	786	
AS	6,455,356	09/2002	Glenn et al.	438	123		
AT	6,468,836	10/2002	DiStefano et al.	438	128		

Foreign Patent Documents							Translation	
		Document	Date	Country	Class	Subclass	Yes	No
072	AU	JP-01128897	05/1989	Japan	B42D	15/02		X
	Examiner: <u>Janet A. Zarach</u> Date Considered: <u>12/6/03</u>							

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				Filing Date January 29, 2002		Group Art Unit 2812 2877		
				U.S. Patent Documents				
*Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate		
DH	AA	5,149,958	09/1992	Hallenbeck et al.	250	216		
	AB	5,264,714	11/1993	Nakaya et al.	257	78		
	AC	5,405,809	04/1995	Nakamura et al.	437	209		
	AD	5,834,835	11/1998	Maekawa	257	680		
	AE	5,834,843	11/1998	Mori et al.	257	723		
	AF	5,859,471	01/1999	Kuraishi et al.	257	666		
	AG	5,893,723	04/1999	Yamanaka	438	65		
	AH	6,265,770	07/2001	Uchiyama	257	698		
	AI							
	AJ							
AK								
AL								
AM								
Foreign Patent Documents								
							Translation	
	Document	Date	Country	Class	Subclass	Yes	No	
DH	AN	JP-57100761	06/1982	Japan	H01L	27/14		X
	AO							
Other Art (Including Author, Title, Date, Pertinent Pages, Etc.)								
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	AQ							
Examiner D. H. Farnh		Date Considered 12/6/3						
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	Filing Date	Group Art Unit 2827

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*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
022	AA	5,081,520	01/1992	Yoshii et al.	357	80	
	AB	5,241,133	08/1993	Mullen, III et al.	174	52.4	
	AC	5,394,303	02/28/95	Yamaji	361	749	
	AD	5,665,652	09/1997	Shimizu	438	127	
	AE	5,674,785	10/1997	Akram et al.	437	217	
	AF	5,744,827	04/28/98	Jeong et al.	257	686	
	AG	5,744,859	04/1998	Ouchida	257	668	
	AH	5,804,771	09/1998	McMahon et al.	174	255	
	AI	5,811,879	09/1998	Akram	257	723	
	AJ	5,949,655	09/1999	Glenn	361	783	
	AK	6,013,877	01/2000	Degani et al.	174	264	
	AL	6,143,588	11/2000	Glenn	438	116	
	AM	6,159,770	12/2000	Tetaka et al.	438	112	
022	AN	6,274,927	08/2001	Glenn	257	680	

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022	AO	Crowley, "Socket Developments for CSP and FBGA Packages," Chip Scale Review, May 1998, pp. 37-40.
	AP	Forster, "Socket Challenges for Chip-Scale Packages," Chip Scale Review, May 1998, pp. 43-47.
	AQ	Amagai, "Chip-Scale Packages for Center-Pad Memory Devices," Chip Scale Review, May 1998, pp. 68-77.
022	AR	Vandeveld et al., "The PSGA, a Lead-Free CSP for High Performance & High Reliable Packaging," Proceedings of the 2001 International Symposium on Microelectronics, October 9, 2001, pp. 260-265.

Examiner <i>David H. Fain</i>	Date Considered 12/6/13
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<b>INFORMATION DISCLOSURE STATEMENT</b> (Use several sheets if necessary)		Applicant Cheng-Lien Chiang	
		Filing Date 1/29/02	Group Art Unit 2827
*Examiner Initial	Other Art (Including Author, Title, Date, Pertinent Pages, Etc.)		
PA	AA	U.S. Application Serial No. 09/865,367, filed May 24, 2001, entitled "Semiconductor Chip Assembly With Simultaneously Electroplated Contact Terminal and Connection Joint"	
PA	AB	U.S. Application Serial No. 09/864,555, filed May 24, 2001, entitled "Semiconductor Chip Assembly with Simultaneously Electrolessly Plated Contact Terminal and Connection Joint"	
PA	AC	U.S. Application Serial No. 09/864,773, filed May 24, 2001, entitled "Semiconductor Chip Assembly With Ball Bond Connection Joint"	
PA	AD	U.S. Application Serial No. 09/878,649 filed June 11, 2001, entitled "Method of Making a Semiconductor Chip Assembly with a Conductive Trace Subtractively Formed Before and After Chip Attachment"	
PA	AE	U.S. Application Serial No. 09/878,626 filed June 11, 2001, entitled "Method of Connecting a Conductive Trace to a Semiconductor Chip"	
PA	AF	U.S. Application Serial No. 09/917,339 filed July 27, 2001, entitled "Method of Connecting a Bumped Compliant Conductive Trace to a Semiconductor Chip"	
PA	AG	U.S. Application Serial No. 09/927,216 filed August 10, 2001, entitled "Semiconductor Chip Assembly with Hardened Connection Joint"	
PA	AH	U.S. Application Serial No. 09/939,140 filed August 24, 2001, entitled "Semiconductor Chip Assembly with Interlocked Conductive Trace"	
PA	AI	U.S. Application Serial No. 09/962,754 filed September 24, 2001, entitled "Method of Connecting a Conductive Trace and an Insulative Base to a Semiconductor Chip"	
PA	AJ	U.S. Application Serial No. 09/972,796 filed October 6, 2001, entitled "Method of Connecting a Bumped Compliant Conductive Trace and an Insulative Base to a Semiconductor Chip"	
PA	AK	U.S. Application Serial No. 09/997,973 filed November 29, 2001, entitled "Method of Connecting a Bumped Conductive Trace to a Semiconductor Chip"	
Examiner	Date Considered		
David H. Fung	12/6/03		
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